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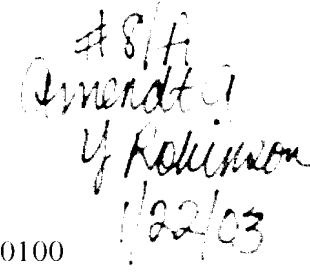
<b>TRANSMITTAL FORM</b> <i>(to be used for all correspondence after initial filing)</i>	<b>Application Number</b>	09/ 915,772	
	<b>Filing Date</b>	July 26, 2001	
	<b>First Named Inventor</b>	Hidetoshi Kusano	
	<b>Group Art Unit</b>	2832	
	<b>Examiner Name</b>	Tuyen T. Nguyen	
<b>Total Number of Pages in This Submission</b>		<b>Attorney Docket Number</b>	075834.00100

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<b>Applicant:</b>	Hidetoshi Kusano	<b>Atty. Docket No.</b>	075834.00100
<b>Serial No.:</b>	09/ 915,772	<b>Group Art Unit:</b>	2832
<b>Filed:</b>	July 26, 2001	<b>Examiner:</b>	Tuyen T. Nguyen
<b>Invention:</b>	"HIGH-FREQUENCY COIL DEVICE AND METHOD OF MANUFACTURING THE SAME"		

Assistant Commissioner of Patents  
Washington, D.C. 20231

In response to the Office Action dated September 20, 2002, please amend the application as follows:

1. (Once Amended) A high-frequency coil [device, characterized by] comprising:  
a dielectric substrate; and  
a coil formed of [a] at least one conductive layer embedded in a [predetermined coil pattern in the] surface of said dielectric substrate, [the bottom surface] and side [surface] surfaces of said coil [being covered by said dielectric substrate] having substantially vertical walls as a result of plating the coil on a temporary base layer that is removed.

2. (Once Amended) The high-frequency coil device as claimed in claim 1, wherein [a recess is formed in the surface of said dielectric substrate, and] said coil [is designed as an aerial wire separated from said dielectric substrate in said recess] has portions which have a gap between a bottom surface of the coil and the substrate.